

**In the Specification:**

Please add a new section directly before the "Technical Field" on page 1 as follows:

**CROSS REFERENCE TO RELATED APPLICATION**

This application is a divisional application of United States Patent Application No. 09/943,897 entitled "WIRE BONDED MICROELECTRONIC DEVICE ASSEMBLIES AND METHODS OF MANUFACTURING SAME," filed on August 30, 2001, now United States Patent No. \_\_\_\_\_, issued on \_\_\_\_\_, which claims foreign priority benefit of Singapore Application No. 200105302-4 filed August 29, 2001, each of which is hereby incorporated by reference in its entirety.